

	TECH	HNICAL DATA SH	IEET	2 /	
STRAIG	HT MALE RECI	R114.424.100 Series : SMB			
	SMT TYPE- RE				
	PACKAGING				
Standard	Unit	Other			
100	'W' option	Contact us			
ELECTRIC	CAL CHARACTE	RISTICS	Е	NVIRONMENTAL	
Impedance Frequency VSWR Insertion loss RF leakage Voltage rating	0-4 1.05 + 0.008 0.03* - (57	$ \begin{array}{l} \Omega \\ GHz \\ x F(GHz) Maxi \\ \sqrt{F(GHz)} dB Maxi \\ - F(GHz)) dB mini \\ Veff Maxi \end{array} $	Operating temp Hermetic seal Panel leakage		
Dielectric withstandin Insulation resistance		Veff mini $M\Omega$ mini	OTHE	ERS CHARACTERISTICS	
			Assembly instr	uction	
MECHANICAL CHARACTERISTICS			Others : * COAXIAL TR	ANSMISSION LINE ONLY	
Center contact retention Axial force – Mating Axial force – Opposi Torque	end 10 te end 10	N mini N mini N.cm mini			
Recommended torque Mating Panel nut	NA	N.cm N.cm			
Mating life Weight	500 0.483	Cycles mini g			

In the effort to improve our products, we reserve the right to make changes judged to be

necessary.



TECHNICAL DATA SHEET

STRAIGHT MALE RECEPTACLE FOR PCB

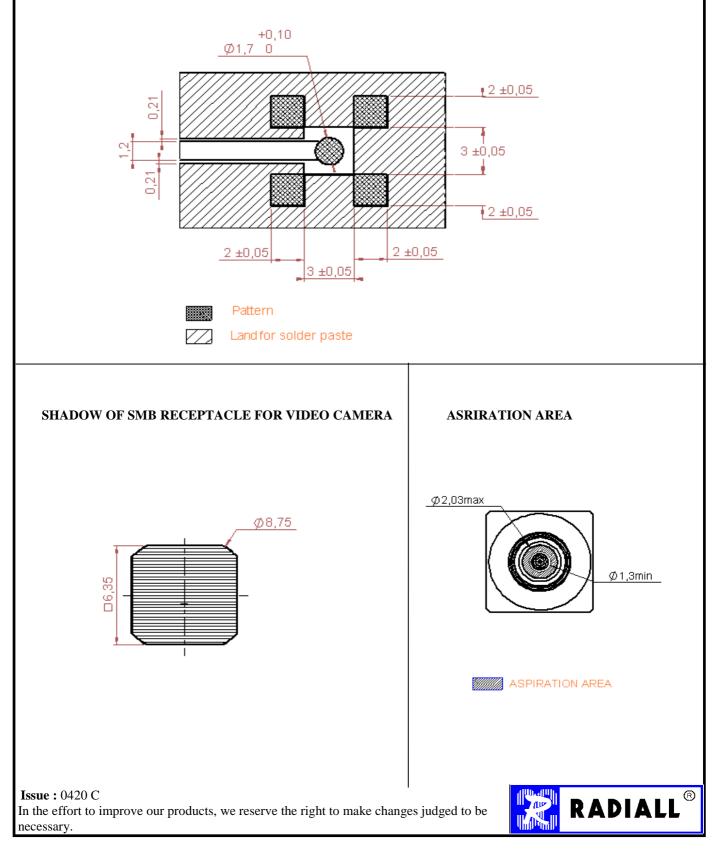
SMT TYPE- REEL OF 100

Series : SMB

R114.424.100

SMB SERIES – INFORMATION

Coplanar line : pattern and signal are on the same side. Thickness of PCB : 1.6 mmThe material of PCB is the epoxy resin of glass fabrics bacs. (Er=4.8). The solder resist should be printed exept for the land pattern on the PCB.



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STRAIGHT MALE RECEPTACLE FOR PCB

SMT TYPE- REEL OF 100

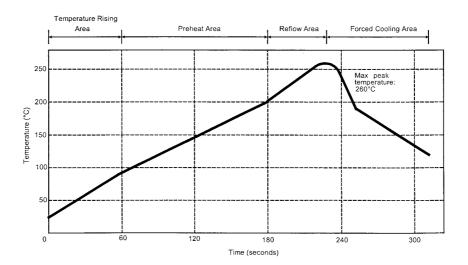
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SOLDER PROCEDURE

- Deposit solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
 We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
- 3. Soldering by infra-red reflow.
- 4. Cleaning of printed circuit boards.
- 5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec



